# Bipolar Transistors - Part 2

### **Chapter 5 of Physics of Semiconductor Devices**

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## Outline

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- 5.4 Related Device Structures Power Transistor Basic Circuit Logics
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  Graded-Base Bipolar Transistor
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## **5.3 Microwave Characteristics**

High  $g_m$  = high current drive = high speed circuits

- Microwave transistors
  - Operation with small signal amplification
- Switching transistors
  - Operation with large-signal transient process (switching between on and off state)
  - E.g. digital circuits



The frequency at which the small signal common-emitter current gain is unity:  $\beta \equiv h_{fe} \equiv \frac{dI_C}{dI_R} = 1 = 0 \text{ dB}$ 



source: www.ess.nthu.edu.tw/ lkschang/letter/course/ch05.pdf



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$$C_{in} = C_{par} + C_{in} + C_{dn} + C_{dp} + C_{DE} + C_{DC} + C_{sc}$$

- $C'_{par}$ : Parasitic capacitance
- $C'_{dn}$ : Diffusion capacitance due to electrons (into base)
- $C'_{dp}$ : Diffusion capacitance due to holes (into emitter)
- $C_{DE}$ : Emitter-base depletion capacitance
- $C'_{DC}$ : Collector-base depletion capacitance
  - $C'_{sc}$ : Space-charge capacitance in collector, due to injected electrons



$$f_T = \frac{g_m}{2\pi C'_{in}} = \frac{1}{2\pi \Sigma (C'/g_m)} = \frac{1}{2\pi \Sigma \tau}$$

 $au = C'/g_m$ : the time constant of the delay due to each capacitance (or the time required to charge each capacitance)  $au = R_C C'_{DC}$ : the time constant in the collector terminal, where  $R_C$ is the total collector resistance

$$f_{T} = \{2\pi[\underbrace{\frac{kT(C_{par} + C_{DE} + C_{DC}')}{qI_{C}}}_{\text{Decrease with current}} + \frac{W^{2}}{\eta D_{n}} + \frac{W_{E}W}{\theta D_{n}} + \frac{W_{DC}}{2\nu_{s}} + R_{C}C_{DC}']\}^{-1}$$

For high-frequency applications, a bipolar transistor should:

- Operate at high current (but less than regime of undesirable high-current effects, e.g. Kirk effect)
- Have a very narrow base thickness
- Have a very narrow collector depletion region



- At low current densities,  $f_T$  increases with  $J_C$ . In this regime the collector current is carried mainly by the drift component
- $J_1$  is the current at which the largest uniform electric field can exist, where  $\mathcal{E}_C=(\phi_{bi}+V_{CB})/\,W_C$
- At  $J_1 = \frac{q\mu_n N_C(\phi_{bi} + V_{CB})}{W_C}$ ,  $f_T$  reaches its maximum. Beyond  $J_1$ , the current cannot be carried totally by the drift component throughout the collector epitaxial region.

### **Small-Signal Characterization, Figures of Merit**

Power gain,  $G_p$ : the ratio of power delivered to the load over the maximum available power to the network.

Stability factor, K: indicates where a transistor will oscillate upon applying a combination of passive load and source impedance with no external feedback.

 $K: \left\{ \begin{array}{ll} >1 & \mbox{the device is unconditionally stable} \\ & \mbox{(will not oscillate)} \\ <1 & \mbox{the device is potentially unstable} \end{array} \right.$ 

Maximum available power gain,  $G_{pmax}$ : the power gain which can be realised by a particular transistor without external feedback

Unilateral gain, U: the forward power gain in a feedback amplifier with its reverse power gain set to zero by adjusting a lossless reciprocal feedback network around the transistor

### **Small-Signal Characterization, Figures of Merit**

Maximum frequency of oscillation,  $f_{max}$ : the frequency at which the unilateral gain becomes unity Noise figure, NF: the ratio of total mean-square noise voltage at the output of the transistor to mean-square noise voltage at the output resulting from thermal noise in the source resistance



### **Switching Characteristics**



- A switching transistor is designed to function as a switch
- The state switches from high-impedance (*off*) condition to low-impedance (*on*) condition in a very short time
- Large signal operation
- E.g. digital circuits
- Usually "on"  $\rightarrow$  saturation



### **Switching Characteristics**



- In saturation,  $Q_B$  rises due to an applied  $I_B$  without increasing  $I_C$
- The change of  ${\cal Q}_B$  gives rise the the transient response
- After the time  $t_{on}$ , the steady-state value of  $Q_B$ :  $Q_B = J_B \tau_n [1 - exp \frac{-t}{\tau_n}]$  $t_{on} = \tau_n ln \left[ \frac{1}{1 - (Q_s/J_B \tau_n)} \right], Q_s = \frac{J_C W^2}{2D_n}$
- At  $t_2,\,I_B$  is turned off and  $Q_B$  decays with time constant  $\tau_n.$
- The storage time  $t_s$  is the time interval for  $Q_B$  to decay from  $J_B\tau_n$  to  $Q_s$  $t_s=\tau_n ln\left(\frac{J_B\tau_n}{Q_s}\right)$
- After  $t_3$ ,  $J_C$  decreases with time constant  $au_n$
- The sum of  $t_s$  and the delay time  $t_d$  is the total turn-off time, which limits the switching speed in digital circuits

### **Device Geometry and Performance**



Cross-sections of silicon bipolar transistors: (a) Conventional structure. (b) Modern single-poly structure with deep trench isolation.

### **Device Geometry and Performance**



Cross-sections of silicon bipolar transistors: (c) Modern double-poly self-aligned structure. (d) Low-performance lateral structure.

## **5.4 Related Device Structures**

- Power Transistor
- Basic Circuit Logics



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- · Designed for power amplification or power switching
  - Must handle high voltages and/or large currents
  - Tradeoff between power and speed  $\rightarrow$  Power usually proportional to  $1/f^2$
- A Safe Operating Area (SOA) defines the collector load lines and bias conditions which safeguard a transistor from the effects described in the next few slides

High-Voltage Limit: HV operation limited by breakdown, typically valued at the off state (i.e.  $V_{BCE0}$ )

• Voltage range can be extended by degrading the current gain



High-Current Effects: Several undesirable effects:

- Base widening due to the Kirk Effect
- Current crowding toward the boundary of the emitter due to the intrinsic base resistance
- In order to obtain high breakdown voltage, must reduce the collector doping  $N_{C}$

 $\rightarrow$  Low  $N_C$  I) exacerbates the Kirk effect and 2) induces region of quasi-saturation due to conductivity modulation in the collector (injected electron density higher than the collector doping)





(a) Common-emitter I-V characteristics showing quasi-saturation at high current and low  $V_{CE}$ . Electron-concentration profiles corresponding to (b) saturation mode (Point-A), (c) quasi-saturation mode (Point-B), and (d) normal mode (Point-C).

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Thermal Runaway: Local catastrophic damage due to positive feedback from raised transistor currents (from elevated temperatures due to power dissipation)

- Performance can be improved by:
  - Encapsulation and packaging with thermal conduction to sink heat
  - Enforce even distribution of current across the entire device area by segmenting the total emitter area into smaller parallel interdigits and adding an emitter resistor over each device to limit undesired current increase
    - $\rightarrow$  Stabilizing resistors or emitter ballasting resistors



Second Breakdown: An abrupt decrease in device voltage with a simultaneous internal constriction of current



- The device must be operated within a certain safe region to avoid permanent damage
- The avalanche breakdown (first breakdown) occurs when the applied emitter-collector voltage reaches  $V_{BCE0}$
- Second breakdown occurs as the voltage increases further
- In real applications, power devices are often under transient biases  $\rightarrow$  High power is dissipated only momentarily
- Higher power can be applied for a short time before destruction occurs (depends on device parameters, e.g. doping concentrations, and geometries, which affect the heat sink efficiency)



### **Basic Circuit Logics**



- (a)
- Basic inverter configuration: input = high  $\rightarrow$  Transistor is on
  - High  $I_C$  develops and IR drop across the load resistor  $R_L$ , pulling output low
- Advantage over FETs: high transconductance of bipolar transistors  $\rightarrow$  high speed
- Disadvantage: delay when switching in and out of saturation



### **Emitter-Coupled Logic, ECL**



- High-speed/high performance circuit, at the expense of high power dissipation
- Transistors arranged and biased such that they never operate in saturation mode (for speed)
- Reference transistor Q2 biased with fixed reference base voltage
- Current I through  $R_E$  held constant
  - Constant I shared between Q1 and Q2, which are coupled by the emitter resistance  $R_{\cal E}$
- When Q1 is on ( $V_{in} > V_{ref}$ ), it steers current away from Q2, which raises the output  $\bar{V}_{out}$
- ECL provides two complementary outputs



### Transistor, Transistor Logic, TCL



- Multiple input gates per transistor  $\rightarrow$  Suitable for dense circuits
- Transistor Q1 has multiple emitter inputs and implements an AND function
- Transistor Q2 is an emitter follower for the lower  $V_{out}$  and an inverter for the upper  $V_{out}$

- TTL is designed for speed
  - When Q2 is turned off from saturation, the base charge is drained quickly as collector current through Q1



### Integrated-Injection Logic, IIL



- Used in IC logic and memories
- Complementary bipolar transistors, i.e. both n-p-n and p-n-p
- The structure incorporates a lateral  $p-n-p \ensuremath{\mathsf{transistor}}$
- The *p*-collector is merged with the base of the vertical n p n transistor
- Note: no resistor is needed
- The circuit is closely packed and does not need isolation between transistors
  - $\rightarrow$  Ease of layout
  - $\rightarrow$  High packing density
- The p-n-p lateral transistor Q1 acts as a current source which injects current into the base of Q2
  - Q2 has multiple collector output contacts

### **BiCMOS**

- · Bipolar transistors have many strong points
  - High  $g_m$ 
    - $\rightarrow$  High speed digital circuits
    - $\rightarrow$  High analog gain
  - Turn-on voltage of a p-n junction is more controllable than the threshold voltage of a  $\operatorname{MOSFET}$
- BiCMOS circuits utilise both bipolar transistors and complementary MOSFETs (CMOS) for optimum design



## 5.5 Heterojunction Bipolar Transistor

- Current gain in a bipolar transistors comes from the injection efficiency of the emitter-base junction
  - · Gain determined by ratio of emitter doping to base doping
- An HBT incorporates a heterojunction as the E-B junction, with a larger bandgap in the emitter
  - $\rightarrow$  Improved injection efficiency
  - $\rightarrow$  Much larger current gain
- · However, gain isn't everything...



(a) Typical structure of an HBT.

b) Special structure using collector-up to minimize the collector capacitance.



### Heterojunction Bipolar Transistor, HBT

- Extra gain can be traded off for other improvements
- In an HBT, the base doping can be higher than the emitter doping, but still maintain a reasonable gain
- High base doping:
  - $\blacksquare$  Lowers the base resistance, which improves  $f_{max}$  and current crowding
  - Improves the Early voltage and reduces high-current effects
- Lower emitter doping:
  - Reduced bandgap narrowing and reduced C<sub>BE</sub>
  - 2 Larger built-in potential
- HBTs are mostly fabricated on III-V compound semiconductors which are capable of providing a semi-insulating substrate  $\rightarrow$  Reduces parasitic capacitance and greatly improves the speed performance

• Current gain: 
$$\frac{J_n}{J_p}|_{HBT} = \left(\frac{n_{iB}^2}{n_{iE}^2}\right) \frac{J_n}{J_p}|_{homojunction}$$
  
=  $\left[exp\left(\frac{\Delta Eg}{kT}\right)\right] \frac{J_n}{J_p}|_{homojunction}$ 





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### **Double-Heterojunction Bipolar Transistor, DHBT**

- One drawback of HBT is  $V_{offset}$  in the common-emitter configuration
  - $V_{offset}$  is because, in the low  $V_{CE}$  region (i.e. saturation) both the base-emitter and the base-collector junctions are under forward bias
  - In an HBT, the base-emitter current is suppressed, so the base-collector current contributes to a negative collector terminal current





### **Double-Heterojunction Bipolar Transistor, DHBT**

- A double-heterojunction bipolar transistor (DHBT) eliminates this drawback by adding a second heterojunction as the base-collector junction
- Other advantages of DHBT:
  - Higher breakdown voltage from a large collector bandgap
  - The high-bangap collector reduces the injection of holes from the base to the collector in the saturation mode

 $\rightarrow$  Reduces the minority charge

 if the collector doping is made higher, it can also reduce high-current effects (e.g. Kirk effect and quasi-saturation)





**Graded-Base Bipolar Transistor** 

Energy-band diagrams for (a) abrupt HBT, (b) graded HBT, (c) graded DHBT, and (d) graded-base bipolar transistor.

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### **Graded-Base Bipolar Transistor**

- A graded HBT is an HBT in which the composition if varied slowly within the depletion region (note: the gain improvement is determined by the total change in bandgap,  $\Delta E_g$ )
- In a graded-base bipolar transistor, the composition is changed gradually within the neutral base region, rather than in the junctions (different function than HBT)
  - The composition grading creates a quasi-field to assist the drift of electrons
- Advantages of graded-base bipolar transistor:
  - Higher electron current and current gain
  - **2** Reduced base charging time for higher  $f_T$
  - Increased Early voltage



### **Hot-Electron Transistor**

- A hot electron is an electron with energy more than a few kT above the Fermi energy
  - $\rightarrow$  The electron is not in thermal equilibrium  $\rightarrow$  Extra kinetic energy  $\rightarrow$  higher velocity  $\rightarrow$  larger current



(a) Electron group velocities as a function of energy above the conduction band.(b) Energy-band diagram of hot-electron based on an abrupt HBT.

### **Hot-Electron Transistor**



Other forms of hot-electron transistors. Hot electrons from: (a) tunneling through a barrier, (b) thermionic emission over a Schottky barrier, and (c) over a planar-doped barrier.

- The speed advantage of a hot-electron transistor has not been demonstrated
- It has been used as a spectrometer to study the properties of hot carriers as a function of their energy

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